PD - 95473



**SMPS MOSFET** 

# IRFB260NPbF

HEXFET<sup>®</sup> Power MOSFET

#### **Applications**

- High frequency DC-DC converters
- Lead-Free

<b>V</b> <sub>DSS</sub>	R <sub>DS(on)</sub> max	Ι <sub>D</sub>
200V	<b>0.040</b> Ω	56A

## **Benefits**

- Low Gate-to-Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective C<sub>OSS</sub> to Simplify Design, (See App. Note AN1001)
- Fully Characterized Avalanche Voltage and Current



#### **Absolute Maximum Ratings**

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	56	
I <sub>D</sub> @ T <sub>C</sub> = 100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	40	7 A
I <sub>DM</sub>	Pulsed Drain Current ①	220	7
$P_{D} @ T_{C} = 25^{\circ}C$	Power Dissipation	380	W
	Linear Derating Factor	2.5	W/°C
V <sub>GS</sub>	Gate-to-Source Voltage	± 20	V
dv/dt	Peak Diode Recovery dv/dt 3	10	V/ns
TJ	Operating Junction and	-55 to + 175	
T <sub>STG</sub>	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )	
	Mounting torqe, 6-32 or M3 screw	10 lbf•in (1.1N•m)	7

## **Thermal Resistance**

	Parameter	Тур.	Max.	Units
R <sub>0JC</sub>	Junction-to-Case		0.40	
R <sub>0CS</sub>	Case-to-Sink, Flat, Greased Surface	0.50		°C/W
$R_{\theta JA}$	Junction-to-Ambient		62	

Notes ① through ⑤ are on page 8

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# Static @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	200			V	$V_{GS} = 0V, I_D = 250 \mu A$
$\Delta V_{(BR)DSS} / \Delta T_J$	Breakdown Voltage Temp. Coefficient		0.26		V/°C	Reference to $25^{\circ}$ C, $I_{D} = 1$ mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			0.040	Ω	$V_{GS} = 10V, I_D = 34A$ ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
IDSS	Drain-to-Source Leakage Current			25	μA	$V_{DS} = 200 V, V_{GS} = 0 V$
USS				250		$V_{DS} = 160V, V_{GS} = 0V, T_J = 150^{\circ}C$
1	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20V$
IGSS	Gate-to-Source Reverse Leakage			-100		V <sub>GS</sub> = -20V

# Dynamic @ $T_J = 25^{\circ}C$ (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
9fs	Forward Transconductance	29			S	V <sub>DS</sub> = 50V, I <sub>D</sub> = 34A
Qg	Total Gate Charge		150	220		I <sub>D</sub> = 34A
Q <sub>gs</sub>	Gate-to-Source Charge		24	37	nC	V <sub>DS</sub> = 160V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge		67	100		V <sub>GS</sub> = 10V ④
t <sub>d(on)</sub>	Turn-On Delay Time		17			V <sub>DD</sub> = 100V
tr	Rise Time		64		ns	I <sub>D</sub> = 34A
t <sub>d(off)</sub>	Turn-Off Delay Time		52			R <sub>G</sub> = 1.8Ω
t <sub>f</sub>	Fall Time		50			V <sub>GS</sub> = 10V ④
Ciss	Input Capacitance		4220			$V_{GS} = 0V$
Coss	Output Capacitance		580			$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance		140		рF	f = 1.0 MHz
Coss	Output Capacitance		5080			$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
Coss	Output Capacitance		230			$V_{GS} = 0V, V_{DS} = 160V, f = 1.0MHz$
C <sub>oss</sub> eff.	Effective Output Capacitance		500			$V_{GS}$ = 0V, $V_{DS}$ = 0V to 160V $\ensuremath{}$

### **Avalanche Characteristics**

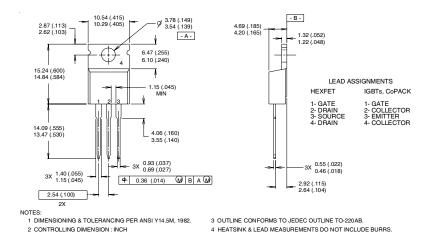
	Parameter	Тур.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>®</sup>		450	mJ
I <sub>AR</sub>	Avalanche Current <sup>®</sup>		34	A
E <sub>AR</sub>	Repetitive Avalanche Energy <sup>①</sup>		38	mJ

#### **Diode Characteristics**

	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current			56		MOSFET symbol
	(Body Diode)			50	A	showing the
I <sub>SM</sub>	Pulsed Source Current				1 ^	integral reverse GL
	(Body Diode) ①		. 220		p-n junction diode.	
V <sub>SD</sub>	Diode Forward Voltage			1.3	V	$T_J=25^\circ C,\ I_S=34A,\ V_{GS}=0V  \textcircled{9}$
t <sub>rr</sub>	Reverse Recovery Time		240	360	ns	$T_{J} = 25^{\circ}C, I_{F} = 34A$
Q <sub>rr</sub>	Reverse RecoveryCharge		2.1	3.2	μC	di/dt = 100A/µs   ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_{S}+L_{D}$ )				

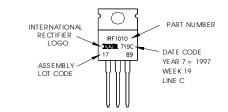
# IRFB260NPbF

# **TO-220AB** Package Outline



# **TO-220AB Part Marking Information**

EXAMPLE: THIS IS AN IRF1010 LOT CODE 1789 ASSEMBLED ON WW 19, 1997 IN THE ASSEMBLY LINE "C" Note: "P" in assembly line position indicates "Lead-Free"



#### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- 3 I\_{SD}  $\leq$  34, di/dt  $\leq$  480A/µs, V\_{DD}  $\leq$  V\_{(BR)DSS}, T\_J  $\leq$  175°C
- ④ Pulse width  $\leq$  300µs; duty cycle  $\leq$  2%.
- $\$  C<sub>oss</sub> eff. is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 to 80% V<sub>DSS</sub>

Data and specifications subject to change without notice. This product has been designed and qualified for the Industrial market.

